

2.3D Package Substrate ~i-THOP®~

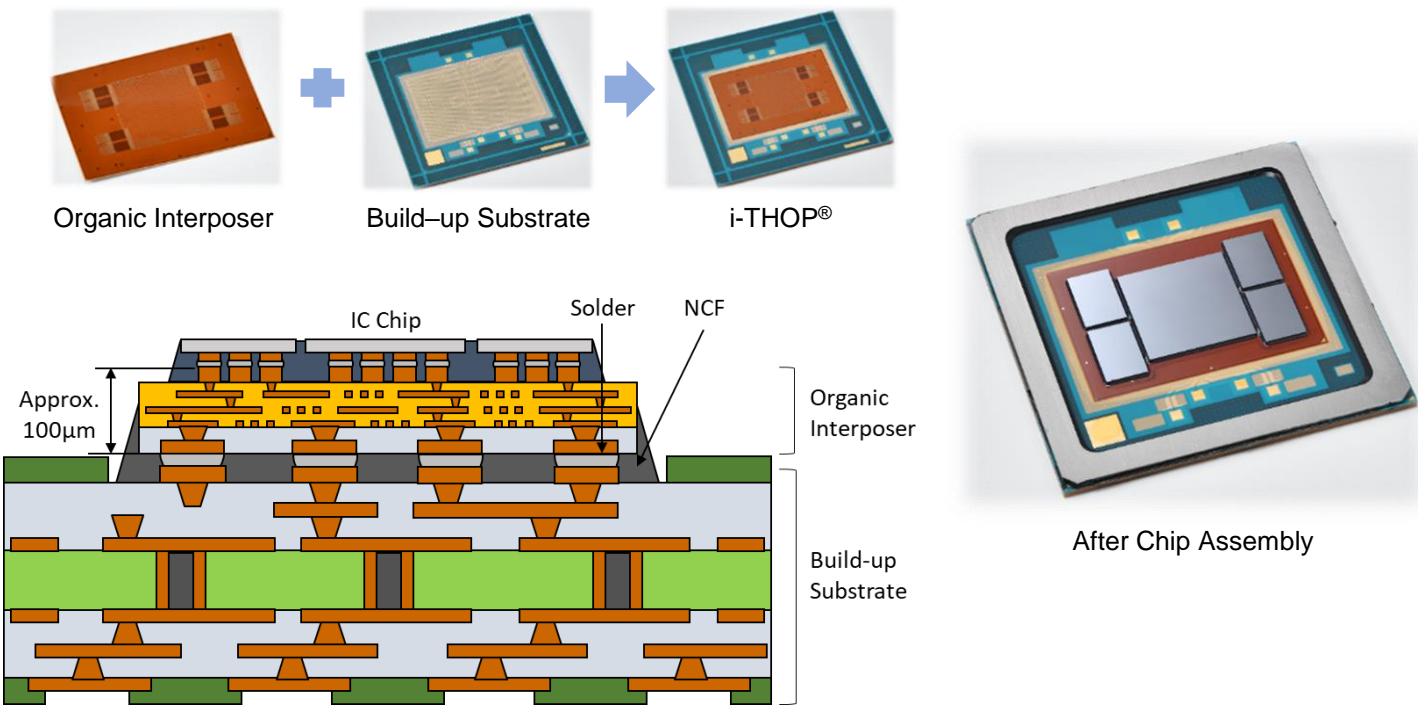
i-THOP (integrated Thin film High density Organic Package) is a registered trademark of SHINKO ELECTRIC INDUSTRIES CO., LTD.

- Under development -

Features

- Ultra-high-density substrate integrating an organic interposer and a build-up substrate enables “chip-last” assembly
- Ultra fine pitch line & space on the interposer using thin film technology
- Large form factor packages to accommodate multiple features such as heterogeneous integration, HBM and chiplets

Structure



Technologies

Organic Interposer	
Min. FC (Flip-Chip) Pad Pitch	40 µm
Min. Line/Space	2 / 2 µm
Micro Via/Via Land Diameter	12 / 21 µm
Metal Thickness	2 µm
Insulation Thickness	5 µm
Interposer Joint	
Material	Sn-Bi Solder
Solder Joint Pitch	150 µm

